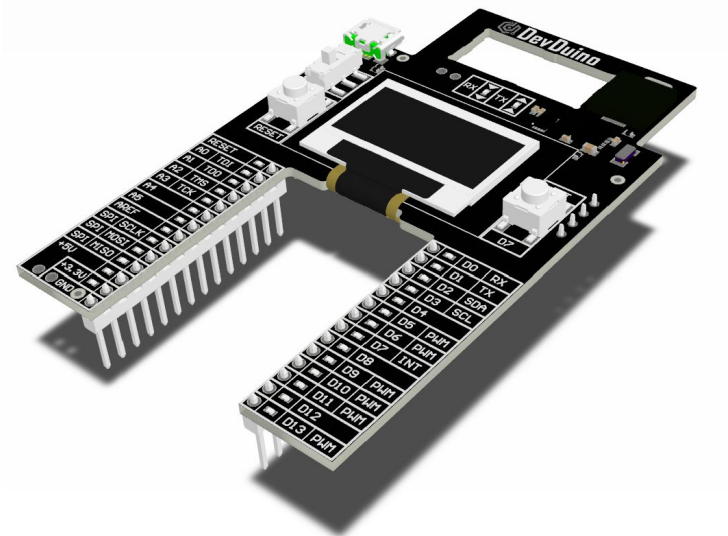




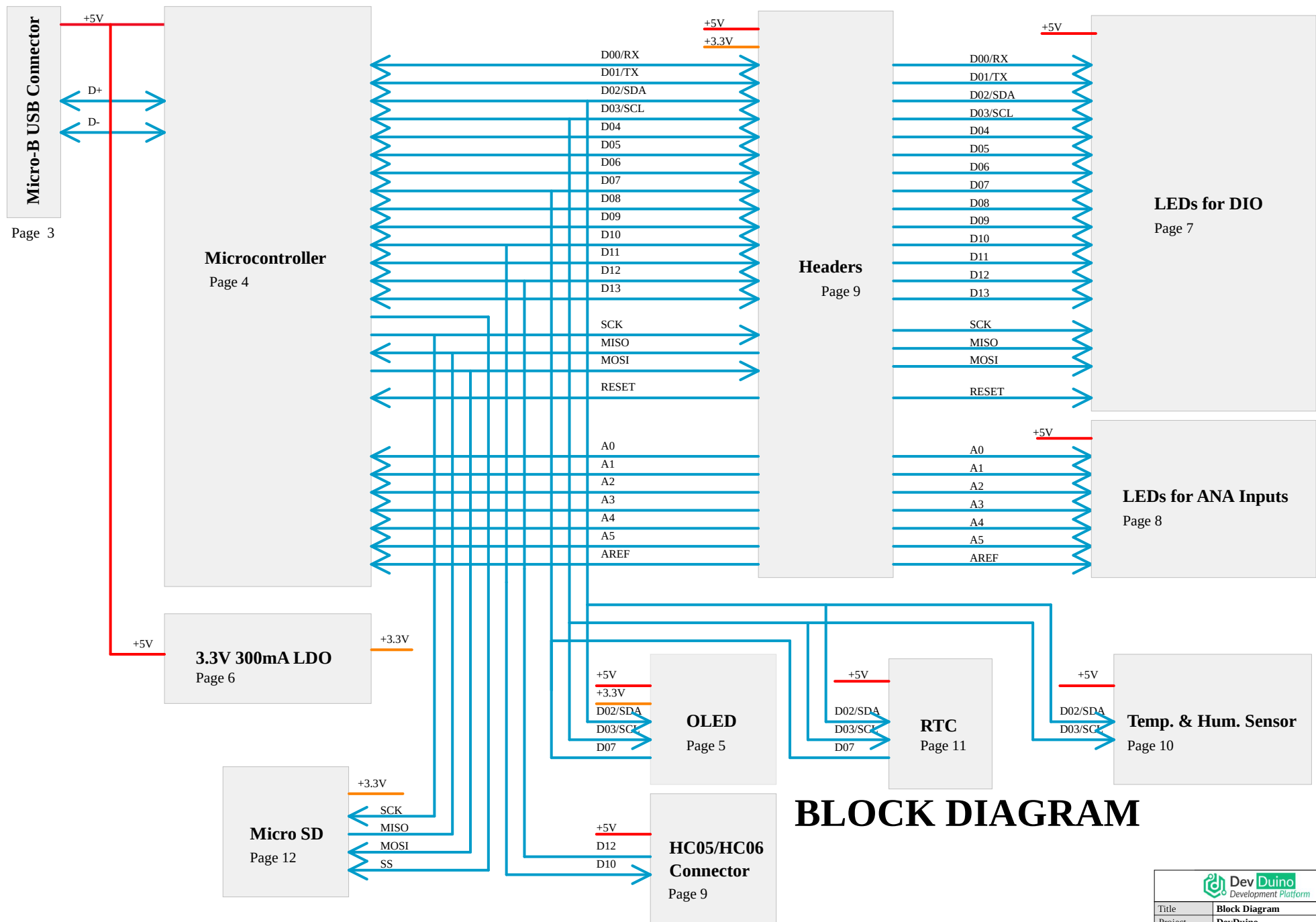
MAIN FEATURES

- # MAIN FEATURES
-
- + ATMEGA32u4 Microcontroller
 - 16 MHz 8-bit AVR
 - 32KB FLASH
 - 2.5KB SRAM
 - 1KB EEPROM
 - 12-channel 10-bit A/D-converter
 - + 1.3" 128x64 OLED Display I2C controlled
 - + REAL TIME CLOCK with Backup BATTERY
 - + MICRO SD Interface
 - + TEMPERATURE & HUMIDITY Sensor
 - + STATUS LEDs on all signals
 - + Power SWITCH and int PUSH-BUTTON
 - + BLUETOOTH HC06/05 Connector
 - + 0.28" VOLTMETER Slot
 - + BREADBOARD Compatible
 - + Breadboard LEDs for NIGHTTIME
 - + ARDUINO Compatible
 - + ROHS Compliant

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11	Real Time Clock
12	Temp. & Hum. Sensor
13	Manufacturing Requirements
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REVISION HISTORY

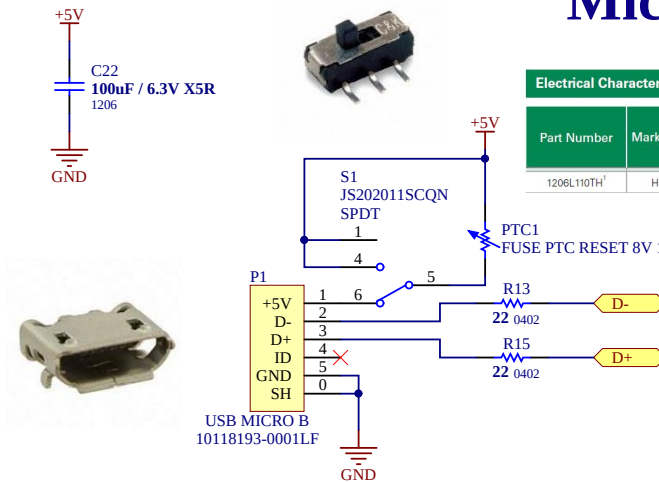
[illegible]



BLOCK DIAGRAM

			
Title	Block Diagram		
Project	DevDuino		
Designed by	Alexandre Pailhoux		
Revision	1.0	Date	June 30th, 2017
Licence	CC BY-NC-SA	Sheet	2 / 14

Micro-B USB Connector



Electrical Characteristics												
Part Number	Marking	I _{hold} (A)	I _{trip} (A)	V _{max} (Vdc)	I _{max} (A)	P _d typ. (W)	Maximum Time To Trip		Resistance		Agency Approvals	
							Current (A)	Time (Sec.)	R _{min} (Ω)	R _{max} (Ω)	UL	CSA
1206L110TH ¹	H	1.10	2.20	8	100	0.8	8.00	0.10	0.040	0.210	X	X

- 2.2.8 D-
USB Full speed / Low Speed Negative Data Upstream Port. Should be connected to the USB D- connector pin with a serial 22Ω resistor.
- 2.2.9 D+
USB Full speed / Low Speed Positive Data Upstream Port. Should be connected to the USB D+ connector pin with a serial 22Ω resistor.

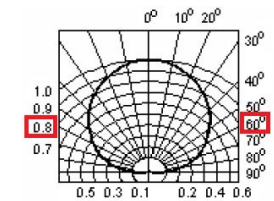
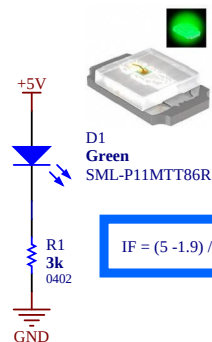
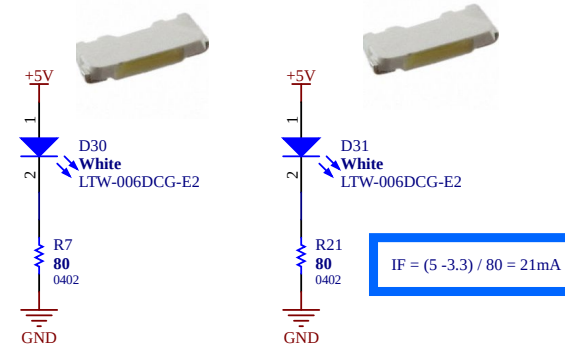


Fig.6 Spatial Distribution

Nighttime LEDs



$$I_F = (5 - 1.9) / 3k = 1mA$$



$$I_F = (5 - 3.3) / 80 = 21mA$$

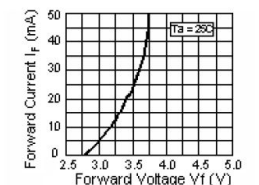


Fig.2 Forward Current vs. Forward Voltage

Specifications

Part No.	Chip Structure	Color	Absolute Maximum Ratings (Ta=25°C)							Electrical and Optical Characteristics (Ta=25°C)									
			Power Dissipation	Forward Current	Reverse Current	Reverse Voltage	Operating Temp.	Storage Temp.	Forward Voltage V _F	Reverse Current I _R	Dominant Wavelength λ _D	Luminous Intensity I _v	Typ.	I _F	Max.	V _S	Min.	Typ.	I _F
			P _D (mW)	I _F (mA)	I _R (mA)	V _{RR} (V)	T _{OP} (°C)	T _{STG} (°C)	(V)	(μA)	(nm)	(mcd)	(V)	(mA)	(mA)	(V)	(mcd)	(mA)	(mA)
SML-P11VT(R)	AlGaNIP	Red	50						1.8		622	626	632		1.8	4.0			
SML-P11UT(R)		Orange	50	20	100 ^{*1}	5	-40~+85	-40~+100	1.8	1	10	5	616	621	626		1.0	2.5	
SML-P11DT(R)		Yellow	50							1.9		601	605	609		1.0	7.3	1	
SML-P11YT(R)		Green	50									583	586	591		1.0	7.6		
SML-P11MT(R)		White	54									566	569	574		1.0	2.1		

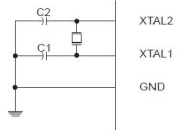
*1: Duty 1/10, 1kHz *2: Measurement tolerance: ±1nm



Title	USB + 5V and DarkEnv LEDs		
Project	DevDuino		
Designed by	Alexandre Pailhoux		
Revision	1.0	Date	June 30th, 2017
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Microcontroller

Figure 6-2. Crystal Oscillator Connections



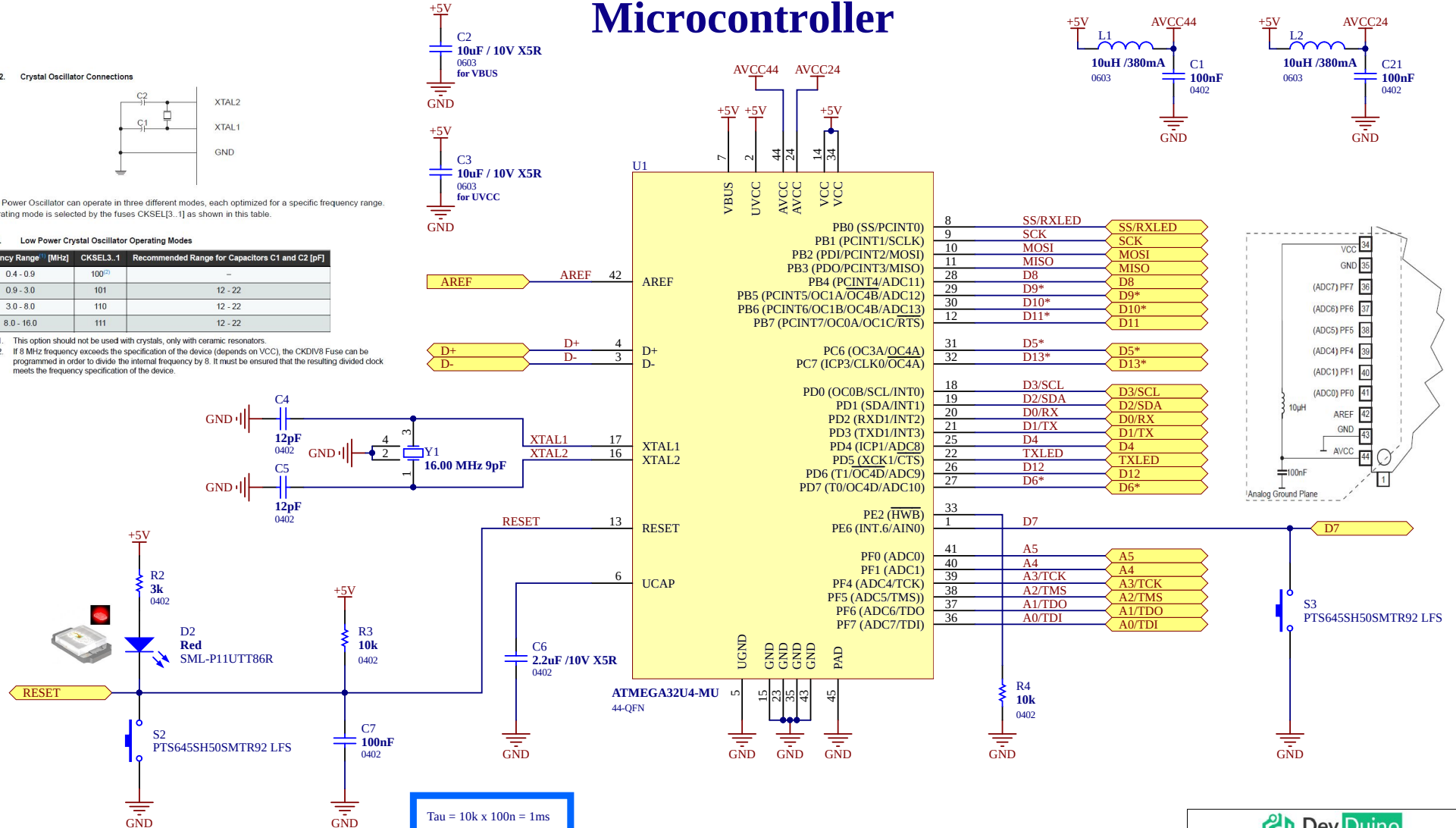
The Low Power Oscillator can operate in three different modes, each optimized for a specific frequency range. The operating mode is selected by the fuses CKSEL[3..1] as shown in this table.

Table 6-3. Low Power Crystal Oscillator Operating Modes

Frequency Range ⁽¹⁾ [MHz]	CKSEL3..1	Recommended Range for Capacitors C1 and C2 [pF]
0.4 - 0.9	100 ⁽²⁾	–
0.9 - 3.0	101	12 - 22
3.0 - 8.0	110	12 - 22
8.0 - 16.0	111	12 - 22

Notes:

1. This option should not be used with crystals, only with ceramic resonators.
2. If 8 MHz frequency exceeds the specification of the device (depends on VCC), the CKDIV8 Fuse can be programmed in order to divide the internal frequency by 8. It must be ensured that the resulting divided clock meets the frequency specification of the device.

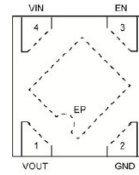
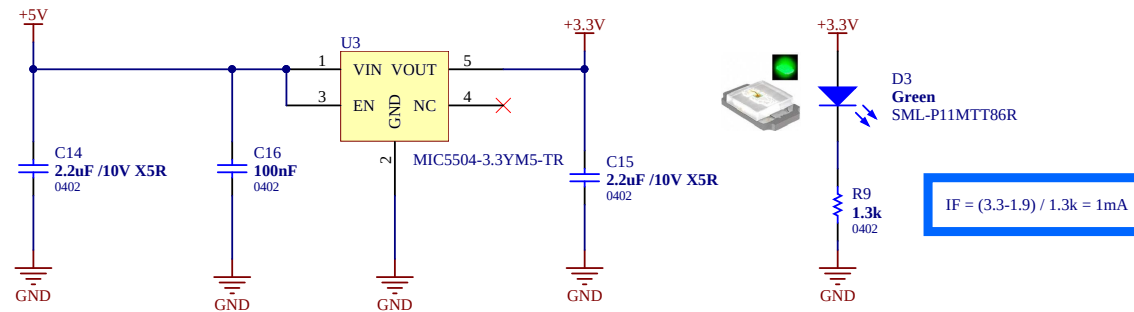


V_{RST}	RESET Pin Threshold Voltage		$0.2V_{CC}$		$0.85V_{CC}$	V
t_{RST}	Minimum pulse width on RESET Pin	5V, 25°C		400		ns

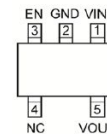
+3.3V LDO

Features

- Input voltage range: 2.5V to 5.5V
- Fixed output voltages from 1.0V to 3.3V
- 300mA guaranteed output current
- High output accuracy ($\pm 2\%$)
- Low quiescent current: 38 μ A
- Stable with 1 μ F ceramic output capacitors
- Low dropout voltage: 160mV @ 300mA
- Output discharge circuit: MIC5502, MIC5504
- Internal enable pull-down: MIC5503, MIC5504
- Thermal-shutdown and current-limit protection
- 4-lead 1.0mm $\times$ 1.0mm Thin DFN package
- MIC5504 5-pin SOT23 package



4-Pin 1mm $\times$ 1mm Thin DFN (MT)
(Top View)



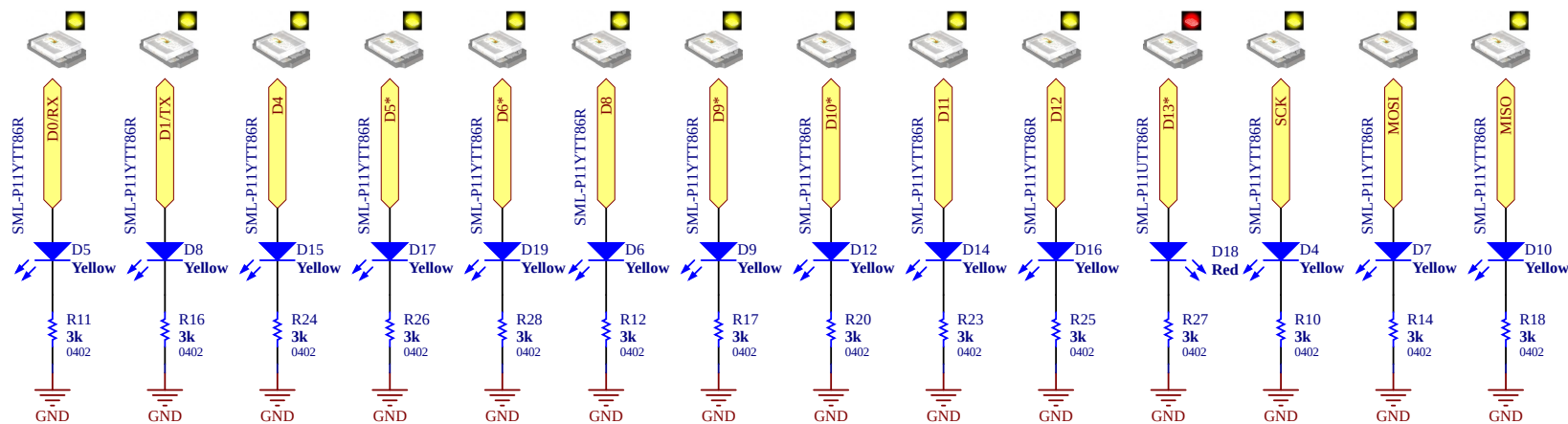
5-Pin SOT23 (M5)
(Top View)

Pin Description

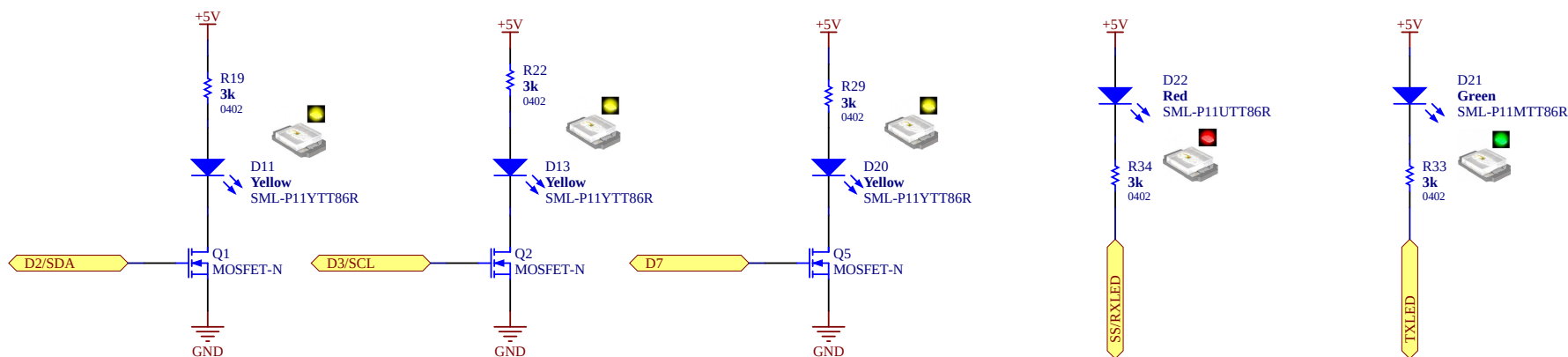
Pin Name	Pin Number Thin DFN-4	Pin Number SOT23-5	Pin Function
VOUT	1	5	Output Voltage. When disabled the MIC5502 and MIC5504 switches in an internal 25 Ω load to discharge the external capacitors.
GND	2	2	Ground
EN	3	3	Enable Input: Active High. High = ON; Low = OFF. For MIC5501 and MIC5502 do not leave floating. MIC5503 and MIC5504 have an internal pull-down and this pin may be left floating.
VIN	4	1	Supply Input.
NC	-	4	No Connection. Pin is not internally connected.
ePad	EP	-	Exposed Heatsink Pad. Connect to GND for best thermal performance.



Title	3.3V LDO		
Project	DevDuino		
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DIGITAL I/O LEDs



Specifications

Part No.	Chip Structure	Output	Absolute Maximum Ratings (Ta=25°C)						Electrical and Optical Characteristics (Ta=25°C)									
			Power Dissipation P _{tot} (mW)	Forward Current I _F (mA)	Reverse Current I _R (mA)	Reverse Voltage V _R (V)	Operating Temp. T _{op} (°C)	Storage Temp. T _{stg} (°C)	Forward Voltage V _F (V)	Reverse Current I _R (µA)	Dominant Wavelength λ _d (nm)	Luminous Intensity I _v (mcd)	Luminous Intensity I _v (mcd)	Luminous Intensity I _v (mcd)	Luminous Intensity I _v (mcd)	Luminous Intensity I _v (mcd)	Luminous Intensity I _v (mcd)	Luminous Intensity I _v (mcd)
SML-P11VT(R)	AlGaInP	Red	50	20	100 ^{*1}	5	-40~+85	-40~+100	1.8	1	10	5	622	626	632	1.6	4.0	1.0
SML-P11UT(R)			52	20	100 ^{*1}	5	-40~+85	-40~+100	1.9	1	10	5	616	621	626	1.0	2.5	1.0
SML-P11DT(R)			52	20	100 ^{*1}	5	-40~+85	-40~+100	1.9	1	10	5	601	605	609	1	7.3	4.0
SML-P11YT(R)			54	20	100 ^{*1}	5	-40~+85	-40~+100	1.9	1	10	5	583	588	591	1	7.6	4.0
SML-P11MT(R)	AlGaInP	Green	54	20	100 ^{*1}	5	-40~+85	-40~+100	1.9	1	10	5	506	509	514	1.0	2.1	1.0
SML-P11MT(R)			54	20	100 ^{*1}	5	-40~+85	-40~+100	1.9	1	10	5	506	509	514	1.0	2.1	1.0

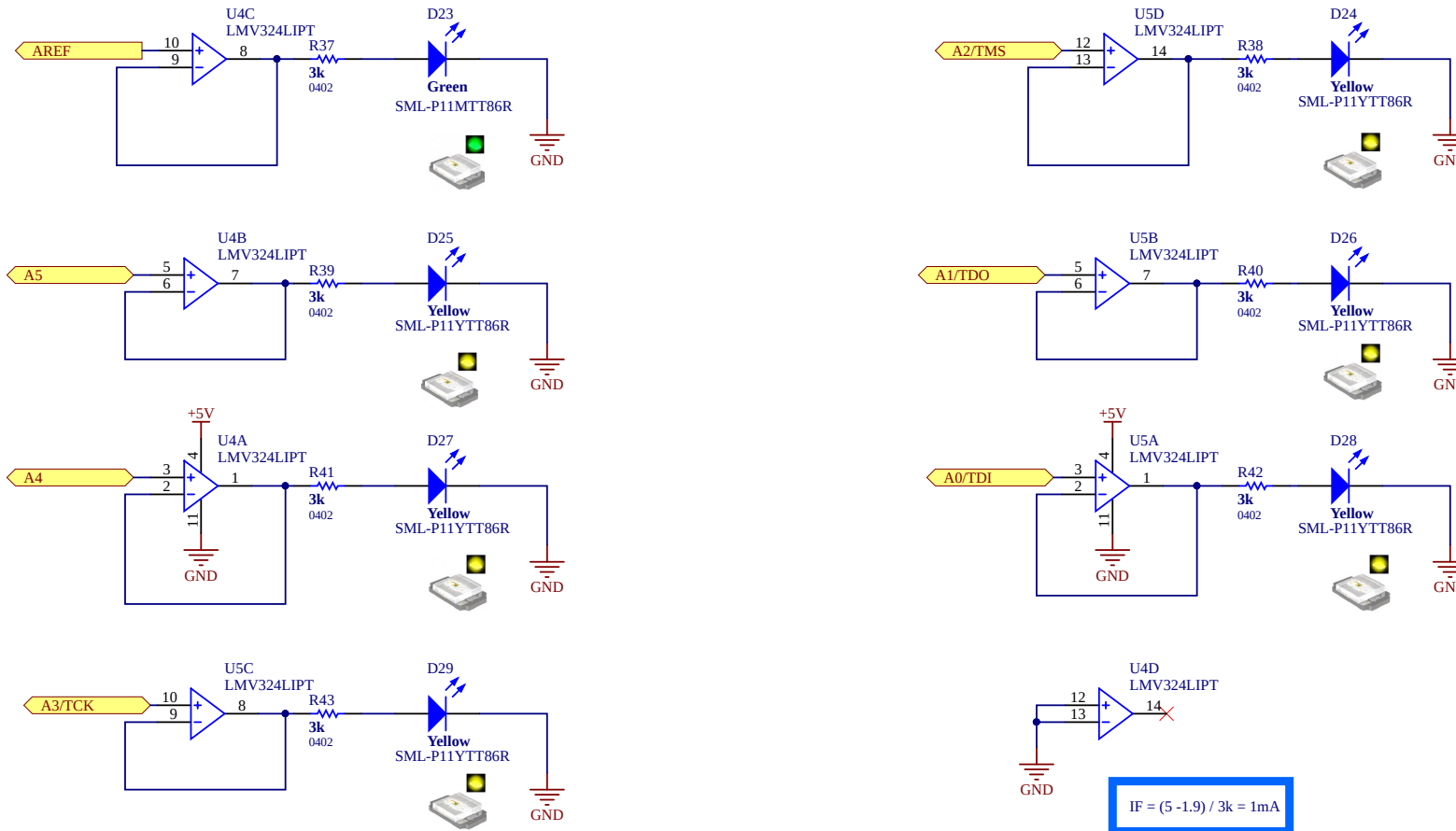
*1 : Duty 1/10, 1kHz *2 : Measurement tolerance : ±1nm

$$I_F = (5 - 1.9) / 3k = 1mA$$



Title	DIO LEDs		
Project	DevDuino		
Designed by	Alexandre Pailhoux		
Revision	1.0	Date	June 30th, 2017
Licence	CC BY-NC-SA	Sheet	7 / 14

BUFFERED ANALOG INPUT LEDs



Specifications

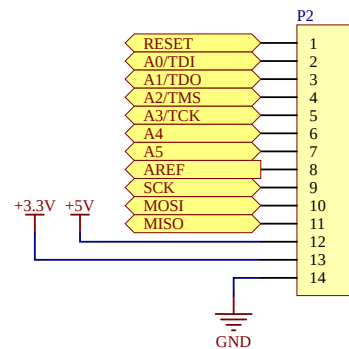
Part No.	Chip Structure	Power	Absolute Maximum Ratings (Ta=25°C)				Electrical and Optical Characteristics (Ta=25°C)									
			Forward Current	Reverse Current	Voltage	Operating Temp.	Storage Temp.	Forward Voltage V _f	Reverse Current I _r	Reverse Current I _s	Dominant Wavelength λ _d			Luminous Intensity I _v		
		P _d (mW)	I _f (mA)	I _r (mA)	V _f (V)	T _{amb} (°C)	T _{stg} (°C)	Typ.	I _r	I _s	Max.	Typ.	Max.	I _v	Min.	Typ.
SML-P11VT(R)	Red	50	20	100 ⁻¹	5	-40~+85	-40~+100	1.8	1	10	5	622	626	632	1.6	4.0
SML-P11UT(R)	Orange	52	20	100 ⁻¹	5	-40~+85	-40~+100	1.9	1	10	5	616	621	626	1.0	2.5
SML-P11DT(R)	Yellow	54	20	100 ⁻¹	5	-40~+85	-40~+100	1.9	1	10	5	601	605	609	1	7.3
SML-P11YT(R)	Green	54	20	100 ⁻¹	5	-40~+85	-40~+100	1.9	1	10	5	583	586	591	1.0	7.6
SML-P11MT(R)	Blue	54	20	100 ⁻¹	5	-40~+85	-40~+100	1.9	1	10	5	506	509	514	1.0	2.1

*1: Duty 1/10, 1kHz *2: Measurement tolerance: ±1nm

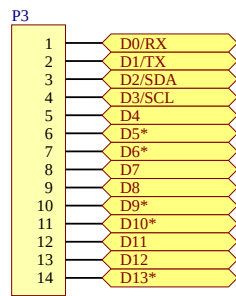


Title	ANA LEDs		
Project	DevDuino		
Designed by	Alexandre Pailhous		
Revision	1.0	Date	June 30th, 2017
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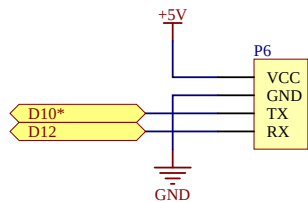
Headers



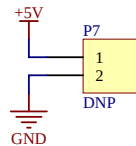
Left Side



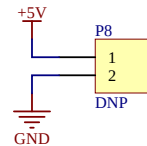
Right Side



For BT Connector



For Voltmeter

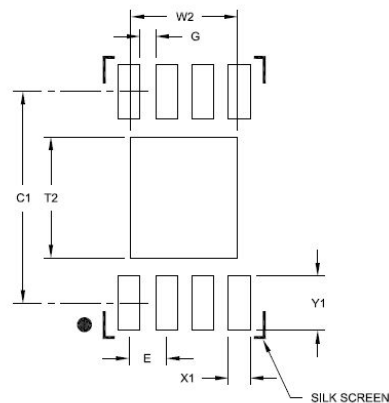


For Power Rails

				
Title	Headers and Connectors			
Project	DevDuino			
Designed by	Alexandre Pailhoux			
Revision	1.0	Date	June 30th, 2017	
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Features

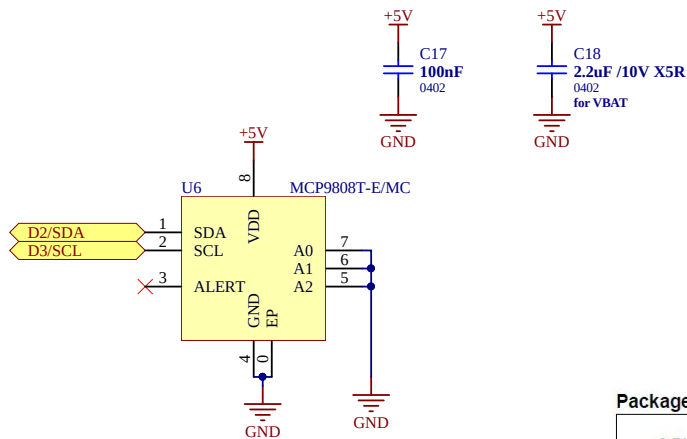
- Accuracy:
 - ± 0.25 (typical) from -40°C to $+125^{\circ}\text{C}$
 - $\pm 0.5^{\circ}\text{C}$ (maximum) from -20°C to 100°C
 - $\pm 1^{\circ}\text{C}$ (maximum) from -40°C to $+125^{\circ}\text{C}$
- User-Selectable Measurement Resolution:
 - $+0.5^{\circ}\text{C}$, $+0.25^{\circ}\text{C}$, $+0.125^{\circ}\text{C}$, $+0.0625^{\circ}\text{C}$
- User-Programmable Temperature Limits:
 - Temperature Window Limit
 - Critical Temperature Limit
- User-Programmable Temperature Alert Output
- Operating Voltage Range: 2.7V to 5.5V
- Operating Current: 200 μA (typical)
- Shutdown Current: 0.1 μA (typical)
- 2-wire Interface: I²C™/SMBus Compatible
- Available Packages: 2x3 DFN-8, MSOP-8



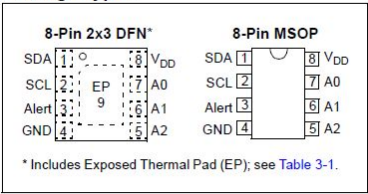
RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	W2			1.45
Optional Center Pad Length	T2			1.75
Contact Pad Spacing	C1		2.90	
Contact Pad Width (X8)	X1			0.30
Contact Pad Length (X8)	Y1			0.75
Distance Between Pads	G	0.20		

Temperature Sensor



Package Types



* Includes Exposed Thermal Pad (EP); see Table 3-1.

6.1 Layout Considerations

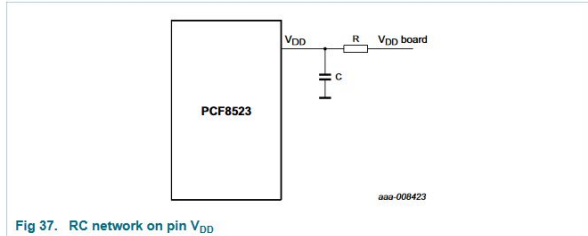
The MCP9808 does not require any additional components besides the master controller in order to measure temperature. However, it is recommended that a decoupling capacitor of 0.1 μF to 1 μF be used between the V_{DD} and GND pins. A high-frequency ceramic capacitor is recommended. It is necessary for the capacitor to be located as close as possible to the power and ground pins of the device in order to provide effective noise protection.

In addition, good PCB layout is key for better thermal conduction from the PCB temperature to the sensor die. For good temperature sensitivity, add a ground layer under the device pins, as shown in Figure 6-1.

Title	Temperature sensor		
Project	DevDuino		
Designed by	Alexandre Pailhoux		
Revision	1.0	Date	June 30th, 2017
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proper functionality of the battery switch-over.

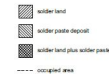
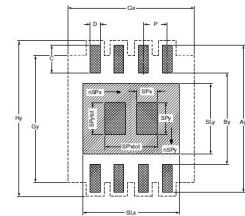
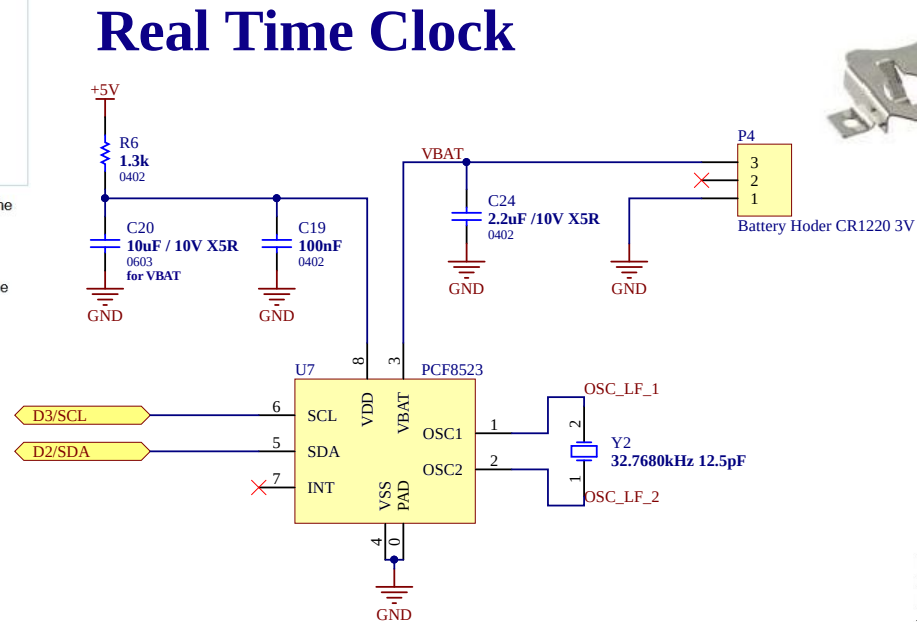
- higher than some mA it is recommended to add an RC network on the V_{DD} pin, as shown in Figure 37.⁵



A series resistor of 1 k Ω and a capacitor of 3.3 μ F assure the proper functionality of the battery switch-over even with very fast V_{DD} slope.

Note that:

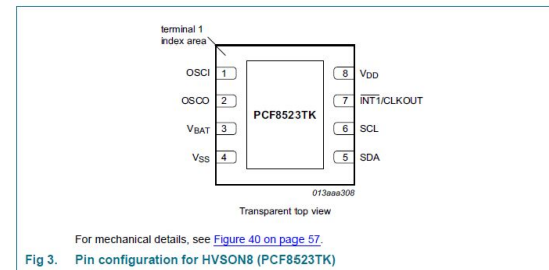
- it is not suggested to assemble a series resistor higher than 2.2 k Ω because of the associated voltage drop
- lower values of capacitors are possible, depending on the V_{DD} slope in the application.



DIMENSIONS in mm												
P	Av	36	C	D	DLA	SLA	SPHASE	SPHASE	SPHASE	SPHASE	SLA	SLA
0.8	4.50	3.35	0.95	0.25	1.25	2.35	1.75	1.1	0.7	1.1	4.25	5.2
Notes: 1. DIMENSIONS ARE IN MILLIMETERS												

2. Features and benefits

- Provides year, month, day, weekday, hours, minutes, and seconds based on a 32.768 kHz quartz crystal
- Resolution: seconds to years
- Clock operating voltage: 1.0 V to 5.5 V
- Low backup current: typical 150 nA at $V_{DD} = 3.0$ V and $T_{amb} = 25$ $^{\circ}$ C
- 2 line bidirectional 1 MHz Fast-mode Plus (Fm+) I²C interface, read D1h, write D0h²
- Battery backup input pin and switch-over circuit
- Freely programmable timer and alarm with interrupt capability
- Selectable integrated oscillator load capacitors for $C_L = 7$ pF or $C_L = 12.5$ pF
- Oscillator stop detection function
- Internal Power-On Reset (POR)
- Open-drain interrupt or clock output pins
- Programmable offset register for frequency adjustment



Title	RTC		
Project	DevDuino		
Designed by	Alexandre Pailhoux		
Revision	1.0	Date	June 30th, 2017
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Micro SD Interface

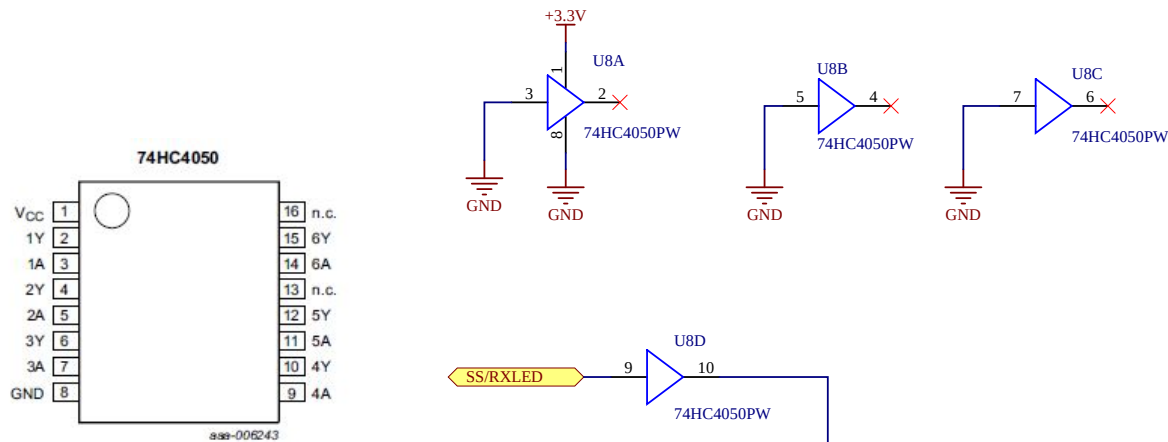
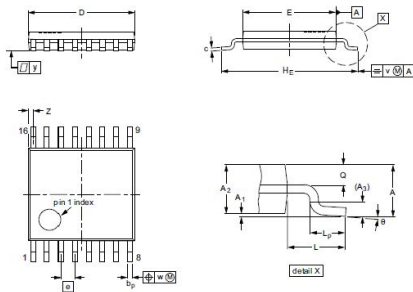
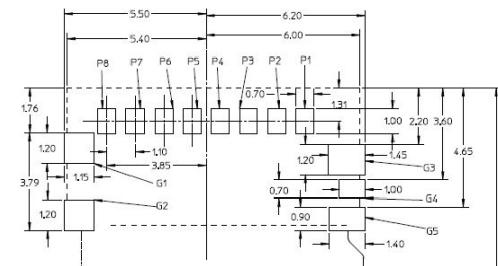


Fig 5. Pin configuration SSOP16 and TSSOP16



DIMENSIONS (mm are the original dimensions)																		
UNIT	A _{max}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	E _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05 0.80	0.95 0.05 0.80	0.25	0.30 0.19 0.11	0.2	5.1 4.9 4.3	4.5 4.3 3.65	6.6 6.2 6.2	1	0.75 0.50 0.50	0.4 0.3 0.3	0.2	0.13	0.1	0.40 0.06 0.06	9° 0° 0°	

 Dev Duino <i>Development Platform</i>			
Title	MicroSD		
Project	DevDuino		
Designed by	Alexandre Pailhoux		
Revision	1.0	Date	June 30th, 2017
Licence	CC BY-NC-SA	Sheet	12 / 14

FIDUCIALS



FIDUCIAL MARK DESIGN SPECIFICATIONS

2.1. Shape

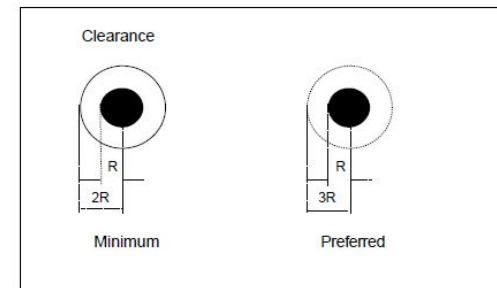
The optimal fiducial mark is a solid filled circle.

2.2. Size

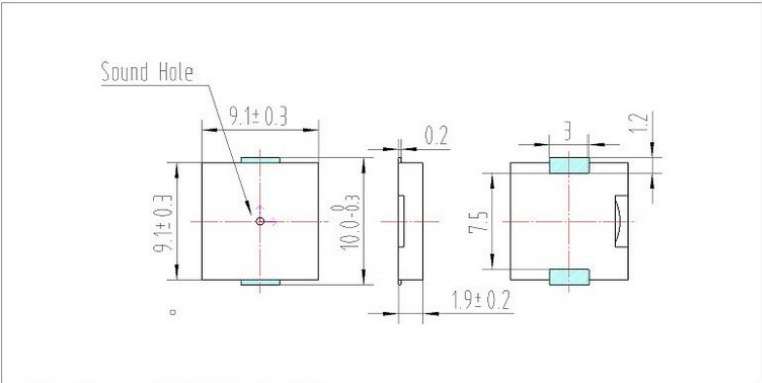
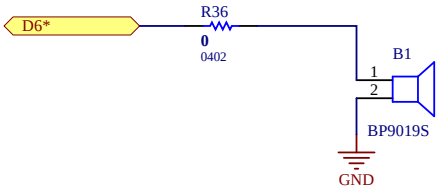
The minimum diameter of the fiducial mark should be 1mm (0.040 in). The maximum diameter of the fiducial should be 3mm (0.120 in). Fiducial marks on the same PCB should not vary in size by more than 25 microns (0.001 in).

2.3. Clearance

A clear area devoid of any other circuit features or markings should be maintained around the fiducial mark. The size of the clear area should be equal to the radius of the mark. A preferred clearance around the mark is equal to the mark diameter.



BUZZER



*Unit: mm; Tolerance: ±0.3mmExcept Specified

*Housing Material: Black LCP

*Terminal plate: 2 soldering pads, tin Plating Brass

3. Piezoelectric Buzzer Model Details

Piezoelectric buzzer Reliability Test

After any following tests the part shall meet specifications without any degradation in appearance and performance except SPL. SPL shall not deviate more than -10 dB from the initial value

1	Resonant Frequency	4000±500Hz
2	Operating Voltage	1~20 Vp-p
3	Rated Current	Max. 1mA ,at 4KHz 50% duty Square Wave 1.5Vp-p
4	Sound Output at 10cm	Min. 65dB,at 4KHz 50% duty Square Wave 1.5Vp-p
5	Capacitance	9000±30%pF at 1KHz
6	Operating Temperature	-30°C~+70°C
7	Store Temperature	-40°C~+85°C
8	Net Weight	Approx 0.2g
9	RoHS	Yes

			
Title	Buzzer		
Project	DevDuino		
Designed by	Alexandre Pailhoux		
Revision	1.0	Date	June 30th, 2017
Licence	CC BY-NC-SA	Sheet	14 / 14

